

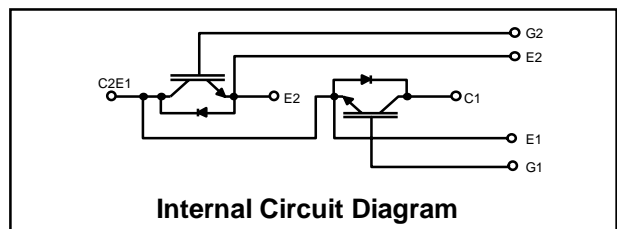
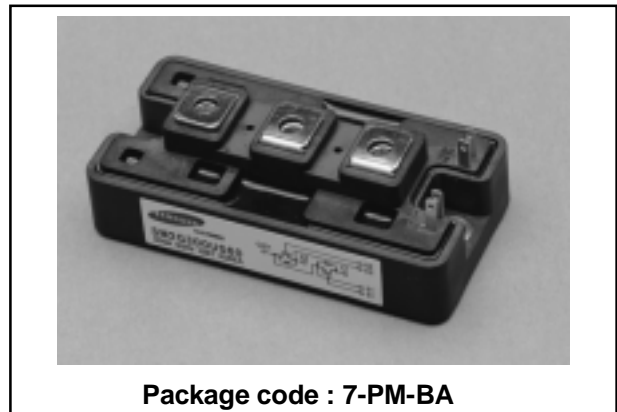
SM2G200US60

FEATURES

- High Speed Switching
- Low Conduction Loss
: $V_{CE(sat)} = 2.1\text{ V (typ)}$
- Fast & Soft Anti-Parallel FWD
- Short circuit rated
: Min 10uS at $T_c=100\text{ }^\circ\text{C}$

APPLICATIONS

- General Purpose Inverters
- Welding Machine
- Induction Heating
- UPS , CVCF
- Robotics , Servo Controls



ABSOLUTE MAXIMUM RATINGS

| Symbol | Characteristics | Rating | Units |
|-------------|---|-----------|------------------|
| V_{CES} | Collector-Emitter Voltage | 600 | V |
| V_{GES} | Gate-Emitter Voltage | ± 20 | V |
| I_C | Collector Current @ $T_c = 25\text{ }^\circ\text{C}$ | 200 | A |
| $I_{CM(1)}$ | Pulsed Collector Current | 400 | A |
| I_F | Diode Continuous Forward Current @ $T_c = 25\text{ }^\circ\text{C}$ | 200 | A |
| I_{FM} | Diode Maximum Forward Current | 400 | A |
| P_C | Maximum Power Dissipation @ $T_c = 25\text{ }^\circ\text{C}$ | 830 | W |
| T_j | Operating Junction Temperature | -40 ~ 150 | $^\circ\text{C}$ |
| T_{stg} | Storage Temperature Range | -40 ~ 125 | $^\circ\text{C}$ |
| Viso | Isolation Voltage @ AC 1 min | 2500 | V |
| | Mounting Torque @ Power terminals screw :M5 | 2.0 | N.m |
| | Mounting screw :M6 | 2.5 | N.m |

Notes: (1) Repetitive Rating : Pulse width Limited by Max.Junction Temperature

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ELECTRICAL CHARACTERISTICS (IGBT PART)

(T_c=25 °C, Unless Otherwise Specified)

| Symbol | Characteristics | Test Conditions | Min | Typ | Max | Units |
|--|--|---|-----|-------|------|-------|
| BV _{CES} | C - E Breakdown Voltage | V _{GE} = 0V , I _C = 250μA | 600 | - | - | V |
| ΔV _{CES} / ΔT _J | Temperature Coeff. of Breakdown Voltage | V _{GE} = 0V , I _C = 1mA | - | 0.6 | - | V/°C |
| V _{GE(th)} | G - E threshold voltage | I _C = 200mA , V _{CE} = V _{GE} | 5 | 6 | 8.5 | V |
| I _{CES} | Collector cutoff Current | V _{CE} = V _{CES} , V _{GE} = 0V | - | - | 250 | uA |
| I _{GES} | G - E leakage Current | V _{GE} = V _{GES} , V _{CE} = 0V | - | - | 100 | nA |
| V _{CE(sat)} | Collector to Emitter saturation voltage | I _C = 200A, V _{GE} = 15V @ T _C = 25 °C | - | 2.1 | 2.7 | V |
| | | I _C = 200A, V _{GE} = 15V @ T _C = 100 °C | - | 2.7 | - | V |
| C _{ies} | Input capacitance | V _{GE} = 0V , f = 1MHz | - | 20000 | - | pF |
| C _{oes} | Output capacitance | V _{CE} = 30V | - | 1680 | - | pF |
| C _{res} | Reverse transfer capacitance | | - | 520 | - | pF |
| td(on) | Turn on delay time | V _{CC} = 300V , I _C = 200A | - | 170 | - | ns |
| tr | Turn on rise time | V _{GE} = 15V | - | 80 | - | ns |
| td(off) | Turn off delay time | R _G = 3.1 Ω | - | 440 | - | ns |
| tf | Turn off fall time | Inductive Load | - | 100 | 250 | ns |
| E _{on} | Turn on Switching Loss | | - | 2.0 | - | mJ |
| E _{off} | Turn off Switching Loss | | - | 6.0 | - | mJ |
| E _{ts} | Total Switching Loss | | - | 8.0 | 16 | mJ |
| T _{sc} | Short Circuit withstand Time | V _{CC} = 300V, V _{GE} = 15V @T _C = 100 °C | 10 | - | - | uS |
| Q _g | Total Gate Charge | V _{CC} = 300V | - | 890 | 1335 | nC |
| Q _{ge} | Gate-Emitter Charge | V _{GE} = 15V | - | 150 | - | nC |
| Q _{gc} | Gate-Collector Charge | I _C = 200A | - | 400 | - | nC |

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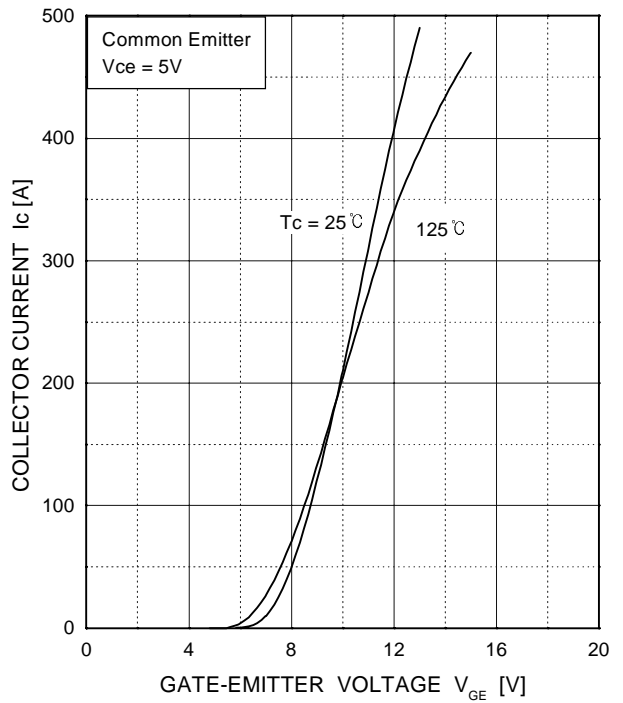
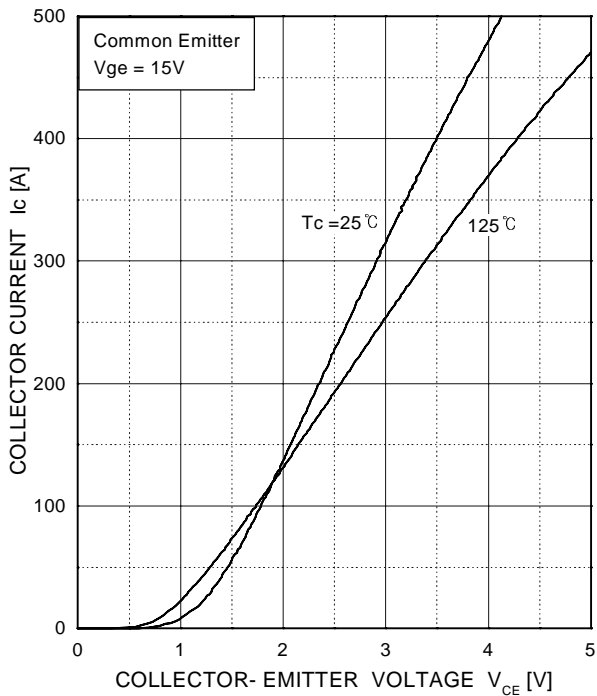
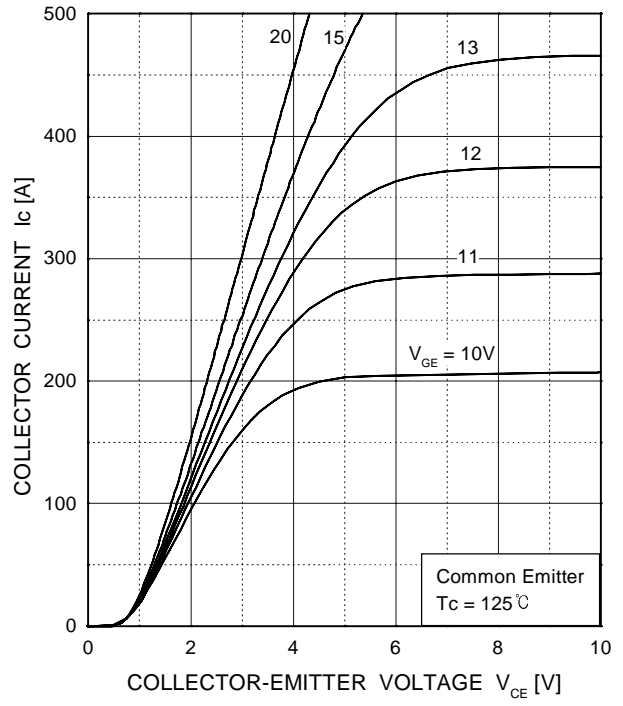
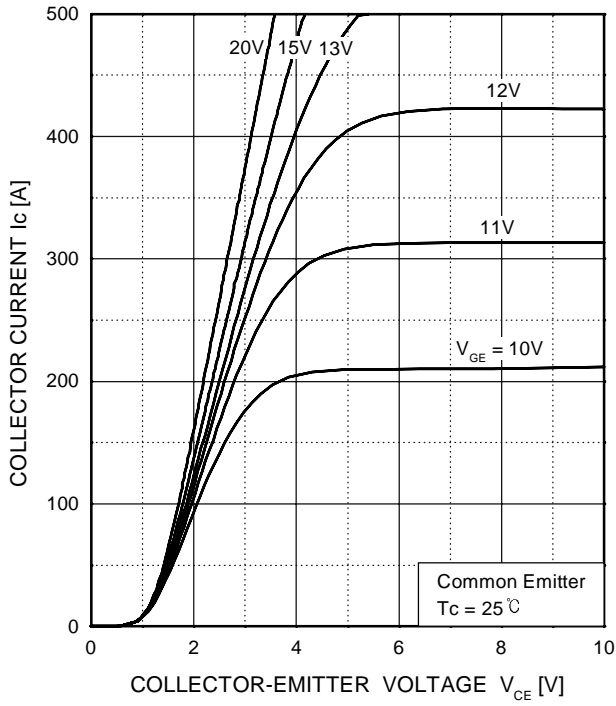
ELECTRICAL CHARACTERISTICS (DIODE PART)

(T_c=25 °C, Unless Otherwise Specified)

| Symbol | Characteristics | Test Conditions | | Min | Typ | Max | Units |
|-----------------|-------------------------------------|---|------------------------|-----|------|------|-------|
| V _{FM} | Diode Forward Voltage | I _F =200A | T _c =25 °C | - | 1.9 | 2.8 | V |
| | | | T _c =100 °C | - | 1.8 | - | |
| T _{rr} | Diode Reverse Recovery Time | I _F =200A, V _R =200V di/dt= -400A/uS | T _c =25 °C | - | 90 | 130 | nS |
| | | | T _c =100 °C | - | 130 | - | |
| I _{rr} | Diode Peak Reverse Recovery Current | I _F =200A, V _R =200V di/dt= -400A/uS | T _c =25 °C | - | 19 | 25 | A |
| | | | T _c =100 °C | - | 25 | - | |
| Q _{rr} | Diode Reverse Recovery Charge | I _F =200A, V _R =200V di/dt= -400A/uS | T _c =25 °C | - | 855 | 1600 | nC |
| | | | T _c =100 °C | - | 1625 | - | |

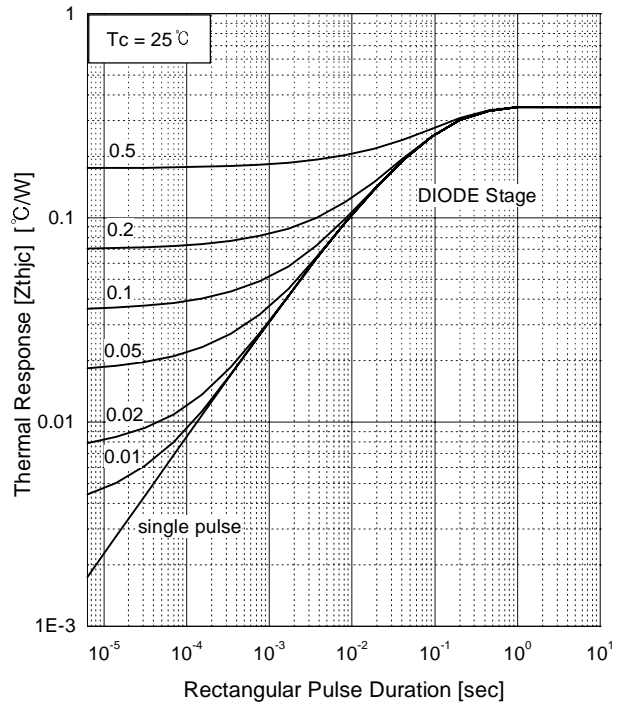
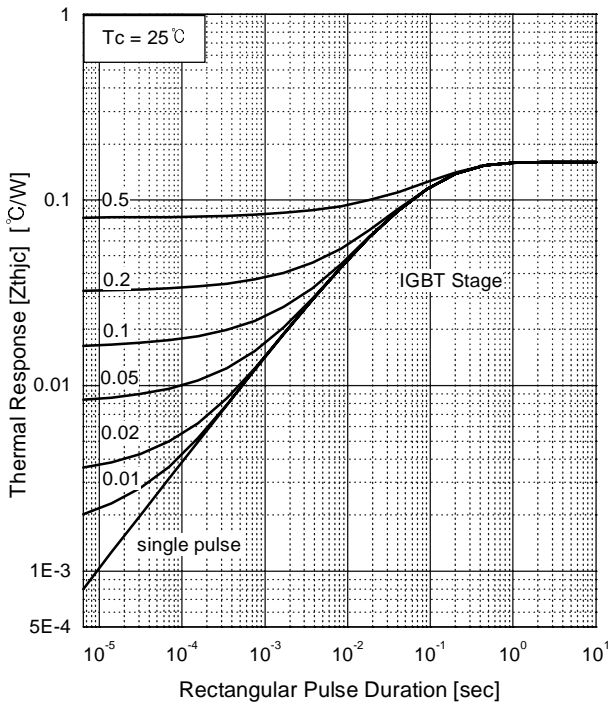
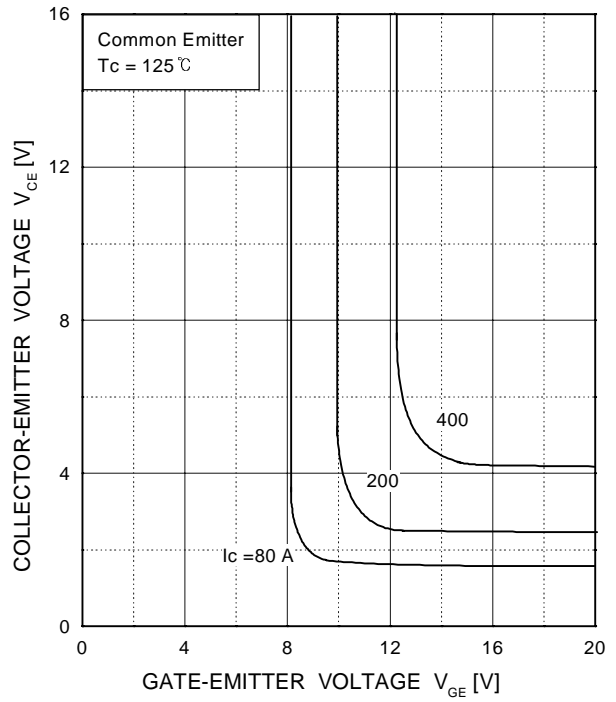
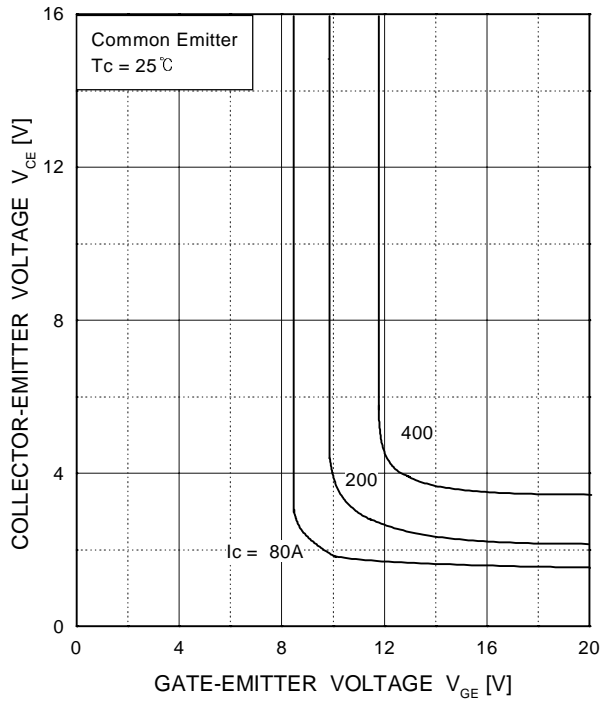
THERMAL RESISTANCE

| Symbol | Characteristics | Typ | Max | Units |
|-------------------|--|-----|------|-------|
| R _θ JC | Junction-to-Case(IGBT Part, Per 1/2 Module) | - | 0.15 | °C/W |
| R _θ JC | Junction-to-Case(DIODE Part, Per 1/2 Module) | - | 0.35 | °C/W |
| R _θ CS | Case-to-Sink (Conductive grease applied) | - | 0.13 | °C/W |
| Weight | Weight of Module | - | 270 | g |



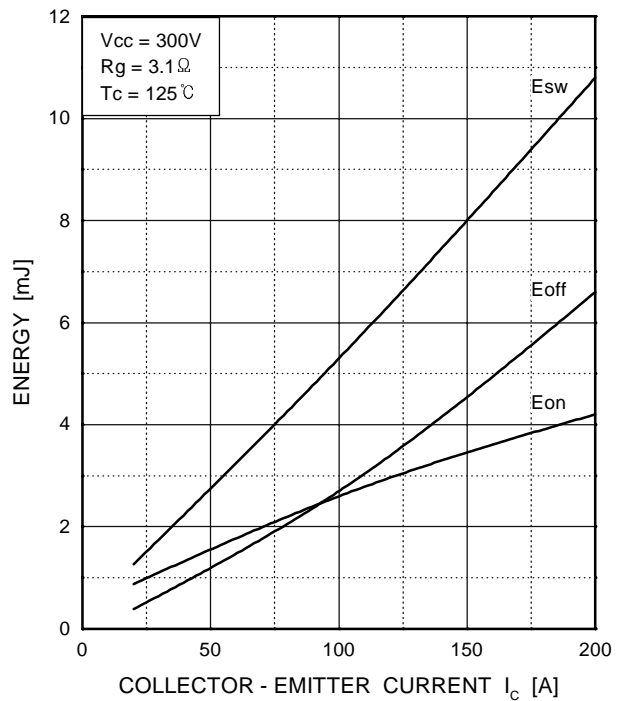
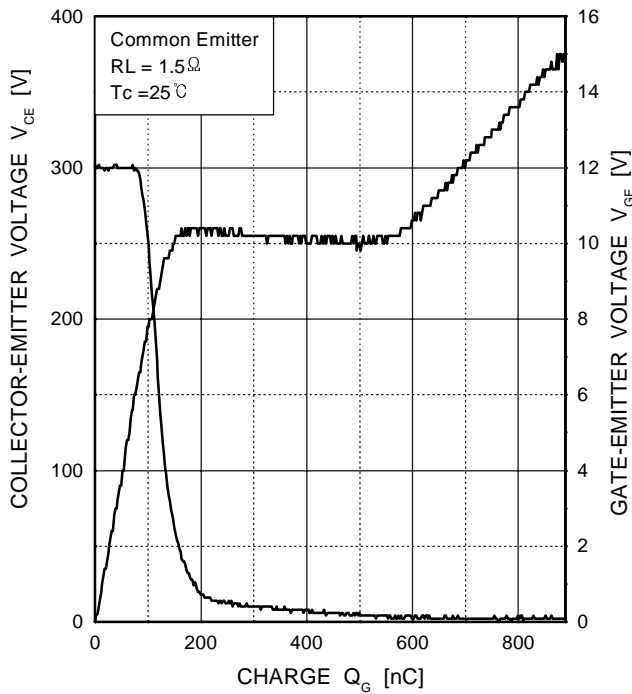
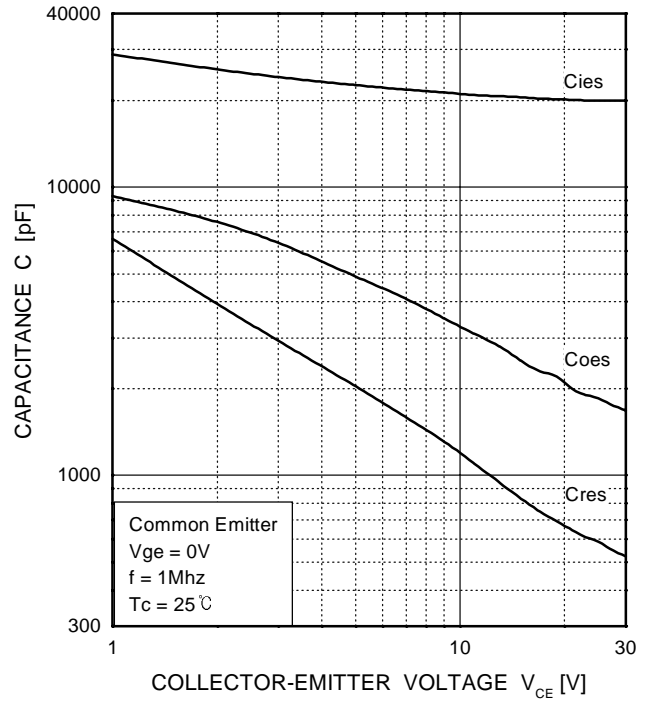
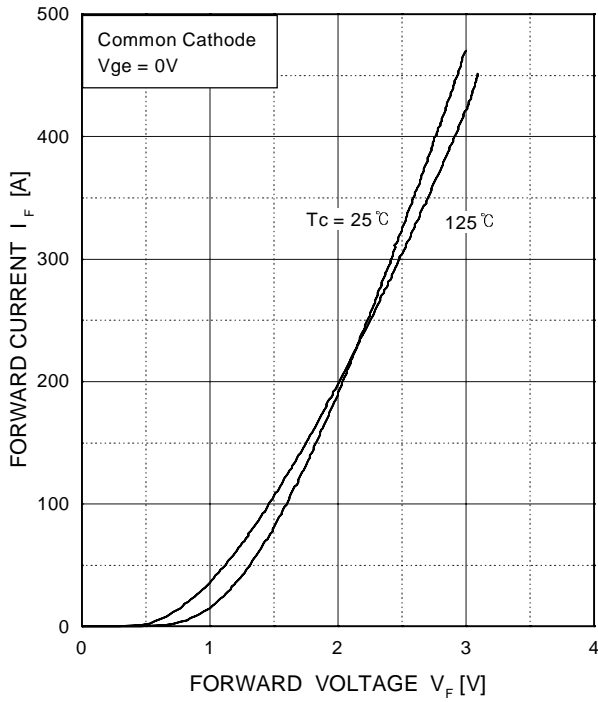
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Preliminary
IGBT MODULE



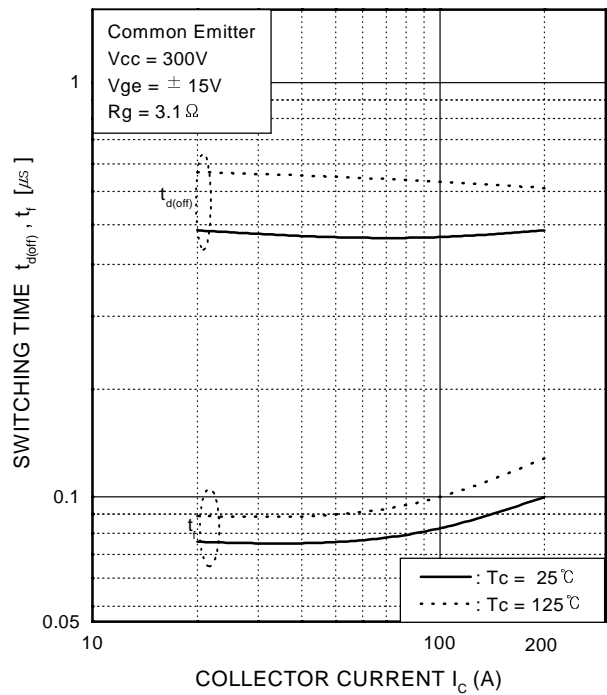
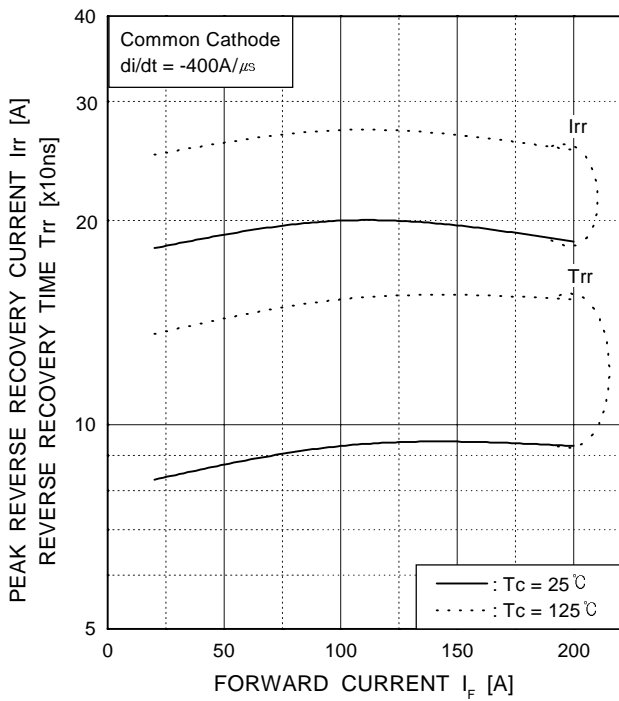
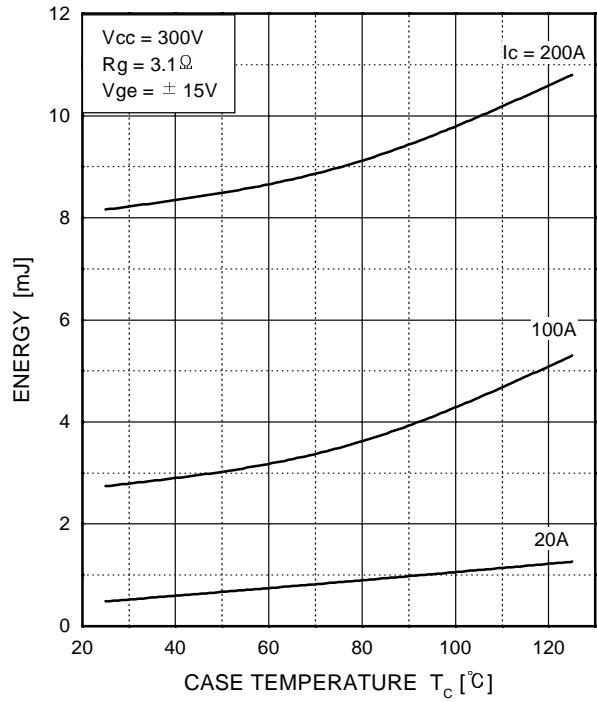
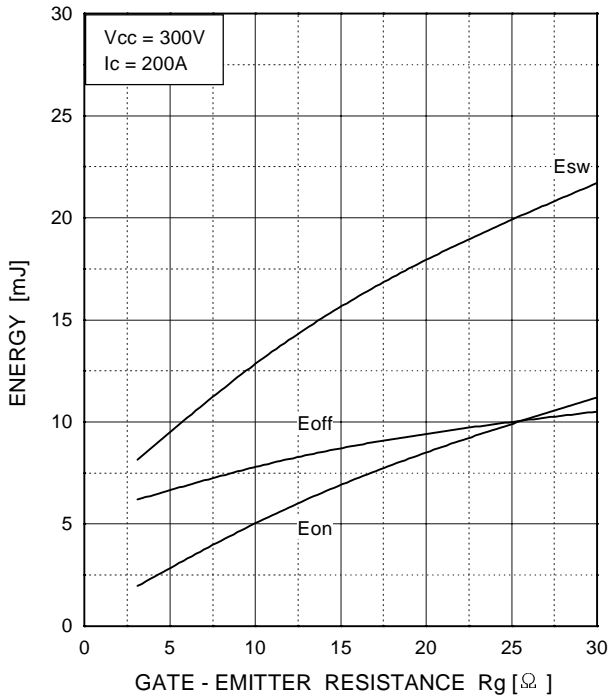
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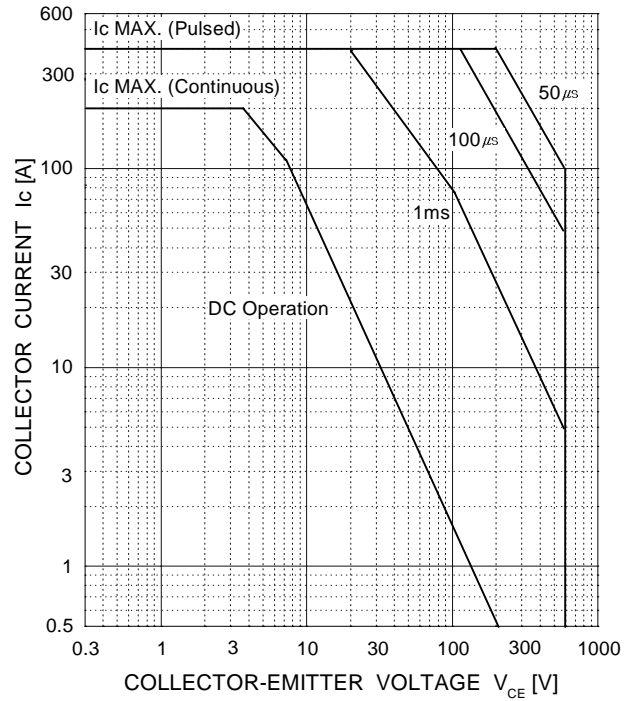
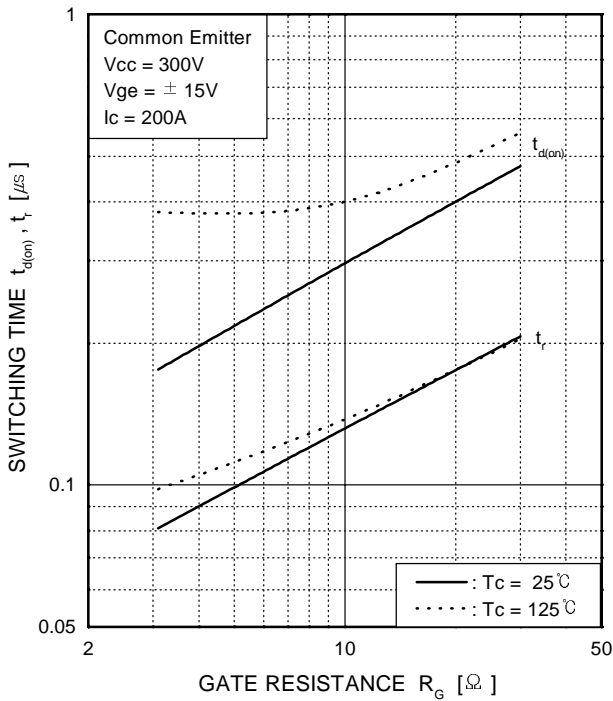
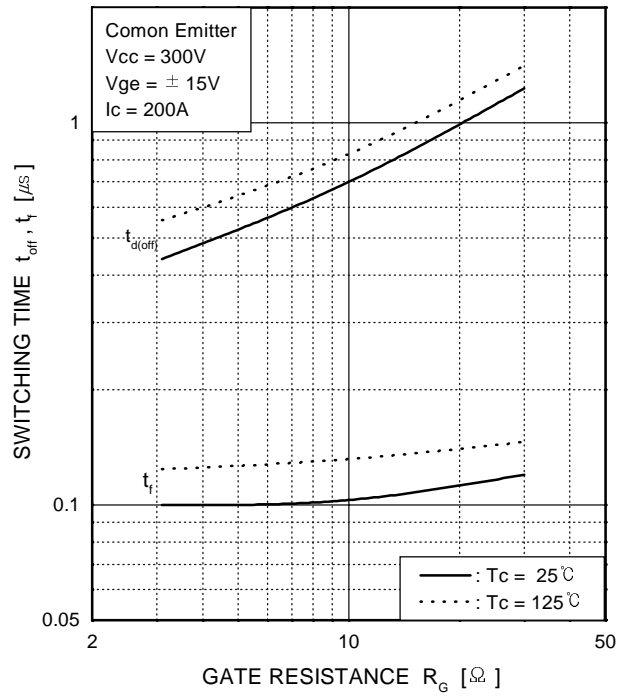
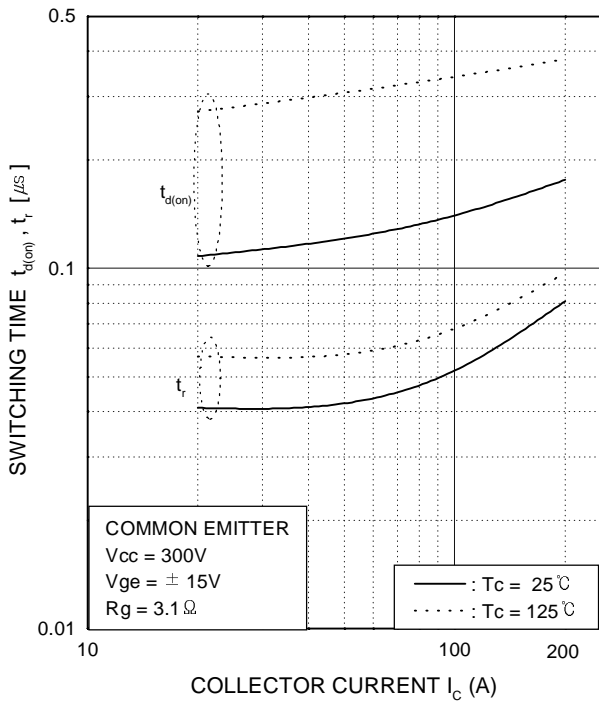
Preliminary IGBT MODULE



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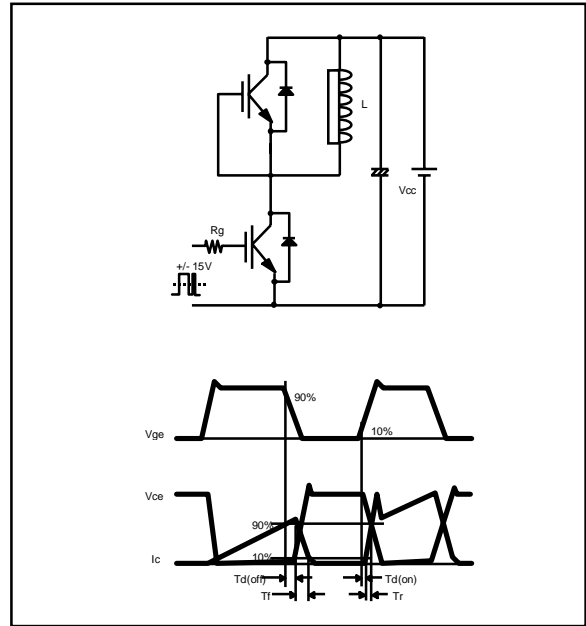
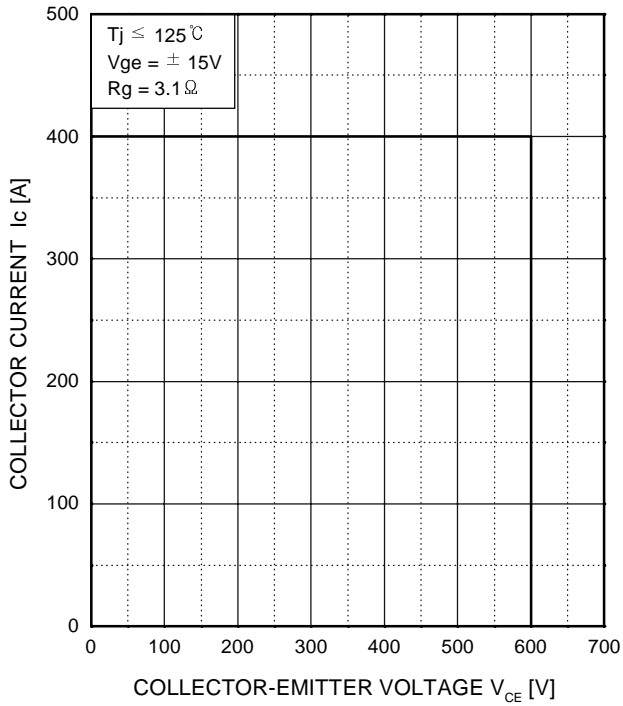
Preliminary
IGBT MODULE





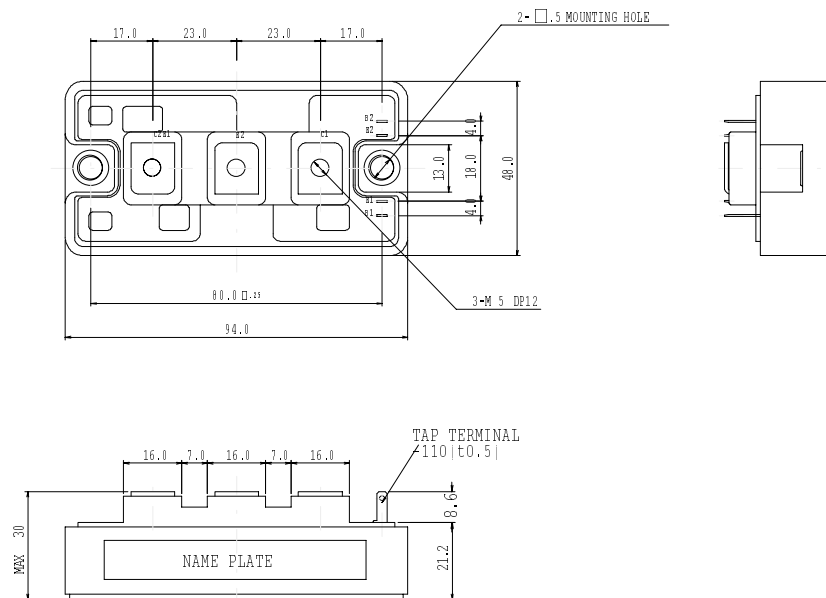
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Preliminary
IGBT MODULE



Inductive Load Test Circuit and Waveforms

7-PM-BA



Unit : mm

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